



- * 1.0 mm Pitch
- * 16x16 Array
- * 4 Perimeter Rows
- * 16 Thermal Balls
- * 17x17 mm Body Size
- * 0.6 mm Solder Ball Diameter

- = Suggested Test Board Trace
- = BGA Package Trace
- = **Do not connect these pads.**
Freescall Internal Use Only.

Looking *through* Package or *at* Test Board